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REMARKS

The application has been reviewed in light of the Office Action dated December 4, 2006. Claims 1-32 were pending, with claims 15-32 having been withdrawn by the Patent Office from examination. By this Amendment, claims 7, 10, and 14 have been canceled, without prejudice or disclaimer, and claims 1, 5, 6, 9 and 13 have been amended to clarify the claimed subject matter. Accordingly, claims 1-6, 8, 9 and 11-13 are presented for reconsideration, with claim 1 being in independent form.

Claims 5, 7, 10 and 14 were objected to under 37 C.F.R. 1.75(c), as purportedly in improper independent form for failing to further limit the subject matter of a previous claim.

By this Amendment, claims 7, 10, and 14 have been canceled, without prejudice or disclaimer, and claim 5 has been amended to clarify the claimed subject matter.

Withdrawal of the objection to the claims is respectfully requested.

Claims 1-14 were rejected under 35 U.S.C. § 102(b) as purportedly anticipated by U.S. Patent No. 6,338,545 (Sekiya '545).

Applicant has carefully considered the Examiner's comments and the cited art, and respectfully submits that independent claim 1 is patentable over the cited art, for at least the following reasons.

This application relates to improved techniques for forming wiring patterns on device substrates. Conventionally, photolithography and screen printing techniques are used for forming patterns on device substrates. However, such conventional techniques typically are not suitable for forming fine patterns.

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Applicant devised a solution jet type fabrication technique which a solution jet type fabrication apparatus comprising a jet head for ejecting a droplet of a solution containing conductive fine particles onto a substrate, so as to form a pattern, by vaporizing a volatile ingredient of the solution, and allowing a solid component to remain on the substrate, wherein the substrate is made from plastic or polymer film and has no liquid absorbing property, the substrate has electrodes thereon, and the jet head includes a nozzle from which the droplet is ejected onto the substrate and electrodes to connect each other, the nozzle being formed from a material that has a greater hardness than that of the fine particles in the solution. Independent claim 1 addresses these features, as well as additional features.

Sekiya '545 is directed to an invention made by Applicant, at an earlier time, wherein liquid jet recording onto a medium such as paper is performed using a fine particle dispersion recording composition. The invention described in Sekiya '545 is suggested to be useful for high-quality and high-resolution inkjet printing by jetting ink droplets onto recording paper.

However, Sekiya '545 neither discloses nor suggests adapting the invention described therein for forming wiring patterns on device substrates. Moreover, Sekiya '545 does not teach or suggest a solution jet type fabrication apparatus comprising a jet head for ejecting a droplet of a solution containing conductive fine particles onto a substrate, so as to form a pattern, by vaporizing a volatile ingredient of the solution, and allowing a solid component to remain on the substrate, wherein the substrate is made from plastic or polymer film and has no liquid absorbing property, the substrate has electrodes thereon, and the jet head includes a nozzle from which the droplet is ejected onto the substrate and electrodes to connect each other, the nozzle being

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formed from a material that has a greater hardness than that of the fine particles in the solution, as provided by the subject matter of amended claim 1.

Applicant maintains that one skilled in the art confronted with the problem of forming fine wiring patterns on device substrates, at the time that the present invention was made by applicant, would not have looked to Sekiya '545 for guidance, since Sekiya '545 does not purport to provide teachings with respect to forming fine wiring patterns on device substrates. That is, one skilled in the art would not have found teaching or suggestion from Sekiya '545 to modify the apparatus described therein to eject droplets of a solution containing conductive fine particles onto a substrate made from plastic or polymer film and having no liquid absorbing property, so as to form a pattern, by vaporizing a volatile ingredient of the solution, and allowing a solid component to remain on the substrate, such that the substrate and electrodes thereon are connected conductively. Sekiya '545 simply does not provide such teachings or suggestions.

Accordingly, for at least the above-stated reasons, Applicant respectfully submits that independent claim 1 and the claims depending therefrom, are patentable over the cited art.

In view of the amendments to the claims and remarks hereinabove, Applicant submits that the application is now in condition for allowance. Accordingly, Applicant earnestly solicits the allowance of the application.

If a petition for an extension of time is required to make this response timely, this paper should be considered to be such a petition. The Patent Office is hereby authorized to charge any fees that are required in connection with this amendment and to credit any overpayment to our Deposit Account No. 03-3125.

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If a telephone interview could advance the prosecution of this application, the Examiner  
is respectfully requested to call the undersigned attorney.

Respectfully submitted,



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